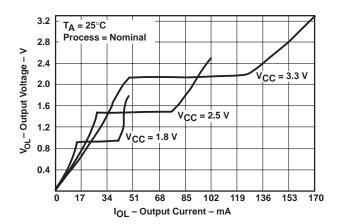
- Member of the Texas Instruments Widebus™ Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC<sup>™</sup> (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I<sub>OH</sub> and I<sub>OL</sub> of ±24 mA at 2.5-V V<sub>CC</sub>
- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Packaged in Plastic Fine-Pitch Ball Grid Array Package

## description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical  $V_{OL}$  vs  $I_{OL}$  and  $V_{OH}$  vs  $I_{OH}$  curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC<sup>TM</sup>) Circuitry Technology and Applications, literature number SCEA009.



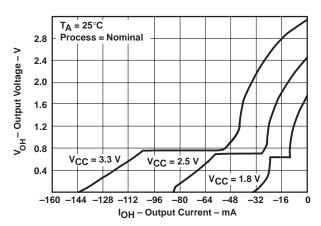


Figure 1. Output Voltage vs Output Current

This 32-bit (dual-octal) noninverting bus transceiver is operational at 1.2-V to 3.6-V  $V_{CC}$ , but is designed specifically for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74AVC32245 is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as four 8-bit transceivers, two 16-bit transceivers, or one 32-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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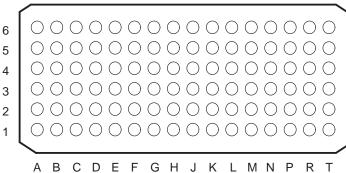


## description (continued)

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC32245 is characterized for operation from -40°C to 85°C.

### **GKE PACKAGE** (TOP VIEW)



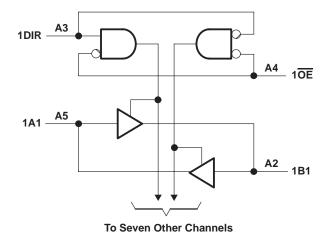
## terminal assignments

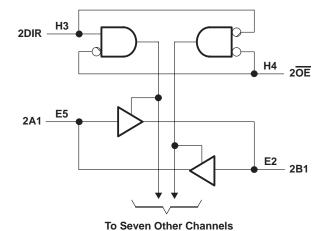
6	1A2	1A4	1A6	1A8	2A2	2A4	2A6	2A7	3A2	3A4	3A6	3A8	4A2	4A4	4A6	4A7
5	1A1	1A3	1A5	1A7	2A1	2A3	2A5	2A8	3A1	3A3	3A5	3A7	4A1	4A3	4A5	4A8
4	1OE	GND	VCC	GND	GND	VCC	GND	2OE	3OE	GND	VCC	GND	GND	VCC	GND	4OE
3	1DIR	GND	VCC	GND	GND	VCC	GND	2DIR	3DIR	GND	VCC	GND	GND	VCC	GND	4DIR
2	1B1	1B3	1B5	1B7	2B1	2B3	2B5	2B8	3B1	3B3	3B5	3B7	4B1	4B3	4B5	4B8
1	1B2	1B4	1B6	1B8	2B2	2B4	2B6	2B7	3B2	3B4	3B6	3B8	4B2	4B4	4B6	4B7
	Α	В	С	D	Е	F	G	Н	J	K	L	М	N	Р	R	Т

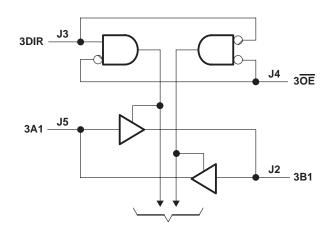
### **FUNCTION TABLE** (each 8-bit transceiver)

INP	UTS	OPERATION				
OE	DIR	OFERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				

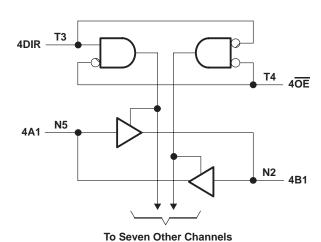
## logic diagram (positive logic)







To Seven Other Channels



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 4.6 V
Input voltage range, V <sub>I</sub> : Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	$0.5 \text{ V}$ to $V_{CC} + 0.5 \text{ V}$
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 4.6 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, I <sub>O</sub>	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3)	40°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



## SN74AVC32245 32-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES191D - MARCH 1999 - REVISED FEBRUARY 2000

## recommended operating conditions (see Note 4)

			MIN	MAX	UNIT					
\/	Supply valtage	Operating	1.4	3.6	V					
Vcc	Supply voltage	Data retention only	1.2		V					
		V <sub>CC</sub> = 1.2 V	VCC							
.,		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	0.65 × V <sub>CC</sub>							
VIН	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>		V					
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7							
		$V_{CC} = 3 V \text{ to } 3.6 V$	2							
		V <sub>CC</sub> = 1.2 V		GND						
		V <sub>CC</sub> = 1.4 V to 1.6 V		0.35 × V <sub>CC</sub>						
VIL	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>	V					
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7						
		V <sub>CC</sub> = 3 V to 3.6 V		0.8						
٧ı	Input voltage	0	3.6	V						
\/-	Output valtage	Active state	0	Vcc	V					
۷o	Output voltage	3-state	0	3.6	V					
		V <sub>CC</sub> = 1.4 V to 1.6 V		-2						
	•	V <sub>CC</sub> = 1.65 V to 1.95 V		-4	A					
IOHS	Static high-level output current <sup>†</sup>	V <sub>CC</sub> = 2.3 V to 2.7 V		-8	mA					
		V <sub>CC</sub> = 3 V to 3.6 V		-12						
		V <sub>CC</sub> = 1.4 V to 1.6 V		2						
	Chatia lavulaval avitavit avinaat	V <sub>CC</sub> = 1.65 V to 1.95 V		4	A					
lols	Static low-level output current <sup>†</sup>	V <sub>CC</sub> = 2.3 V to 2.7 V		8	mA					
		V <sub>CC</sub> = 3 V to 3.6 V		12						
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 1.4 V to 3.6 V		5	ns/V					
TA	Operating free-air temperature	-	-40	85	°C					

T Dynamic drive capability is equivalent to standard outputs with I<sub>OH</sub> and I<sub>OL</sub> of ±24 mA at 2.5-V V<sub>CC</sub>. See Figure 1 for V<sub>OL</sub> vs I<sub>OL</sub> and V<sub>OH</sub> vs I<sub>OH</sub> characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC*<sup>TM</sup>) *Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# PRODUCT PREVIEW

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	V <sub>CC</sub>	MIN	TYP†	MAX	UNIT	
		I <sub>OHS</sub> = -100 μA		1.4 V to 3.6 V	V <sub>CC</sub> -0.	.2			
V <sub>OH</sub>		$I_{OHS} = -2 \text{ mA},$	V <sub>IH</sub> = 0.91 V	1.4 V	1.05				
		$I_{OHS} = -4 \text{ mA},$	V <sub>IH</sub> = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V <sub>IH</sub> = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V <sub>IH</sub> = 2 V	3 V	2.3				
		I <sub>OLS</sub> = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	V <sub>IL</sub> = 0.49 V	1.4 V			0.4		
V <sub>OL</sub>		$I_{OLS} = 4 \text{ mA},$	V <sub>IL</sub> = 0.57 V	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	$V_{IL} = 0.7 V$	2.3 V			0.55		
		$I_{OLS} = 12 \text{ mA},$	$V_{IL} = 0.8 \ V$	3 V			0.7		
II	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
l <sub>off</sub>		$V_I$ or $V_O = 3.6 V$		0			±10	μΑ	
loz‡		$V_O = V_{CC}$ or GND		3.6 V			±12.5	μΑ	
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μА	
C.	Control inputs	V. – V. a. or CND		2.5 V				n.E	
Ci	Control inputs	$V_I = V_{CC}$ or GND	CC of GIAD					pF	
C.	A or B ports	Vo = Voo or GND		2.5 V				7	
C <sub>io</sub>	A OI D POILS	$V_O = V_{CC}$ or GND		3.3 V				pF	

<sup>†</sup> Typical values are measured at  $T_A = 25$ °C.

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

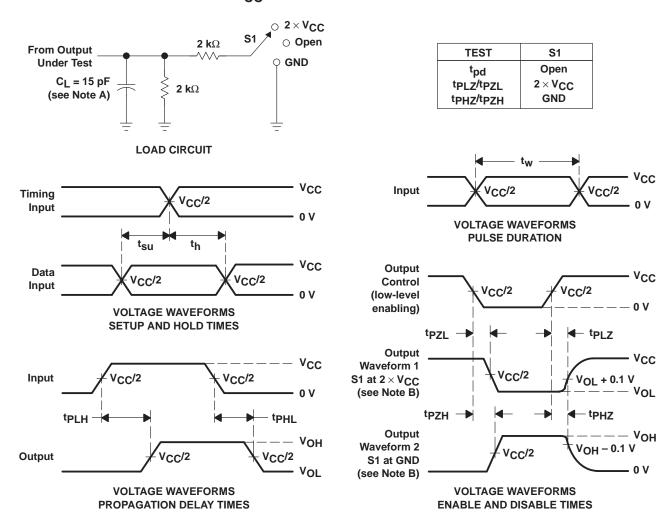
PARAMETER	FROM (INPUT)	-	TO (OUTPUT)	V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> =	1.5 V 1 V	V <sub>CC</sub> =		V <sub>CC</sub> =		V <sub>CC</sub> = ± 0.3		UNIT
		(001101)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t <sub>pd</sub>	A or B	B or A										ns	
t <sub>en</sub>	ŌE	A or B										ns	
<sup>t</sup> dis	ŌĒ	A or B							·			ns	

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER			TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
Γ	` .	Power dissipation	Outputs enabled	Cı = 0. f = 10 MHz				pF
1,	Ppd	capacitance	Outputs disabled	$C_L = 0$ , $f = 10 MHz$				þг

<sup>‡</sup> For I/O ports, the parameter IOZ includes the input leakage current.

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.2 \text{ V}$ AND 1.5 V $\pm$ 0.1 V



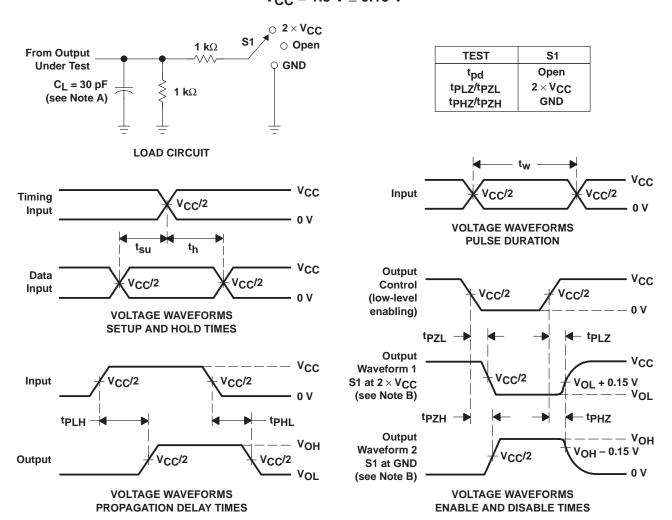
- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.  $t_f \leq 2$  ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms



## PRODUCT PREVIEW

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

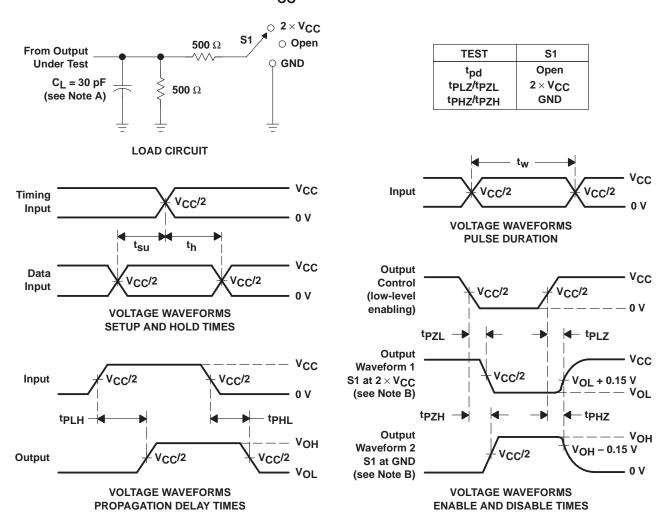


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

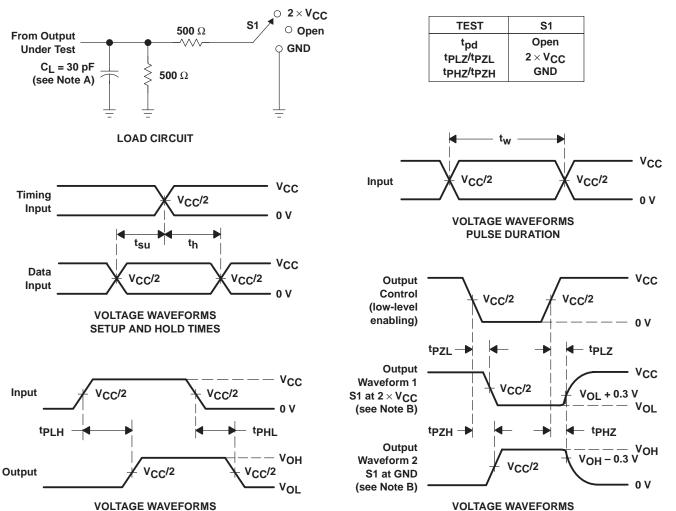
Figure 4. Load Circuit and Voltage Waveforms



**ENABLE AND DISABLE TIMES** 

## PRODUCT PREVIEW

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.

PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



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